


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/17/9976	
1.3 Title of PCN	Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for selected products in LQFP packages	
1.4 Product Category	Listed LQFP 32 7x7, LQFP 44 10x10, LQFP 48 7x7 & LQFP 64 10x10 packaged products	
1.5 Issue date	2017-02-27	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK WOLINSKI
2.1.2 Phone	+49 89460062287
2.1.3 Email	frank.wolinski@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

4. Description of change

	Old	New
4.1 Description	Current locations : Stats ChipPAC Shanghai China (SCC), Amkor ATP Philippines and ST Muar Malaysia	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. Amkor ATP Philippines and ST Muar Malaysia locations remain. See more information on PCN 9976 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change on form fit function. Lead color and surface finish may change depending on leadfinishing.	

5. Reason / motivation for change

5.1 Motivation	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only LQFP packaged products listed.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability is described in PCN9976_Additional information attached document
------------------------	---

7. Timing / schedule

7.1 Date of qualification results	2017-05-19
7.2 Intended start of delivery	2017-06-19
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	9976 PCN9976_PCN10011_RERMCD1621- LQFP JSCC- MCD QA reliability plan.pdf
------------------------	--

8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-27
--	----------------------------	------------	------------

9. Attachments (additional documentations)	
9976 Public product.pdf 9976 PCN9976_Additional information.pdf 9976 PCN9976_PCN10011_RERMCD1621- LQFP JSCC- MCD QA reliability plan.pdf	

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F030C6T6	
	STM32F030CCT6	
	STM32F030K6T6	
	STM32F030R8T6	
	STM32F031C4T6	
	STM32F051R8T6	
	STM32F070RBT6	
	STM32F100C6T6B	
	STM32F100C8T6B	
	STM32F100C8T6BTR	
	STM32F100C8T7B	
	STM32F100CBT6B	
	STM32F100CBT6BTR	
	STM32F100RCT6B	
	STM32F101CBT6	
	STM32F101RBT6TR	
	STM32F101RCT6	
	STM32F101RET6	
	STM32F101RFT6TR	
	STM32F103C8T6	
	STM32F103CBT6	
	STM32F103R8T6	
	STM32F103R8T6TR	
	STM32F103RBT6	
	STM32F103RBT6TR	
	STM32F103RCT6	
	STM32F103RCT6TR	
	STM32F103RET6	
	STM32F105R8T6	
	STM32F105RBT6	
	STM32F205RCT6	
	STM32F446RCT6	
	STM32L100R8T6	
	STM32L100RBT6	
	STM32L100RBT6TR	
	STM32L100RCT6	
	STM32L151R8T6	
	STM8S005K6T6C	
	STM8S105K4T6C	
	STM8S105S4T6C	
	STM8S105S6T6C	

	STM8S207C8T6	
	STM8S207RBT6	
	STM32F070RBT6TR	
	STM32F101C6T6A	
	STM32P101RFMBP	
	STM32F205RBT6TR	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics – All rights reserved